Visit Amkor at the IMAPS 9th International Conference and Exhibition on Device Packaging

Amkor Technology invites you to join us at the IMAPS 9th International Conference and Exhibition on Device Packaging being held March 12-14, 2013 at the Radisson Fort McDowell Resort and Casino, Scottsdale / Fountain Hills, Arizona, USA.

Ron Huemoeller, Senior Vice President of Advanced Product / Platform Development at Amkor is the General Chair-elect for Device Packaging Professional Development Courses (PDCs), and Russell Shumway, Director of MEMS & Sensor Packaging at Amkor, is this year's Technical Co-Chair of the MEMS & Microsystems Workshop session.

Amkor is pleased to be exhibiting at the show (visit us at Booth #47) and our technical staff will be presenting eight papers at this year's conference, including:

- **Tues. 11:00-11:30 AM**
  **Thermal Modeling Approach for Enhancing TCNCP Process for Manufacturing Fine Pitch Copper Pillar Flip Chip Packages** by Siddharth Bhopte, Jesse Galloway, Kyung-Rok Park, Hyun-Jin Park, Jeong-Han Choi, Ho-Beob Yu and Sung-Hwan Yang

- **Tues. 3/12 11:30-12:00 PM**
  **Groove Geometry and Mold Shrinkage Effects on Die Stress in Flip Chip Molded BGAs (FCmBGA)** by Bora Baloglu, Corey Reichman, Miguel Jimarez, Ahmer Syed

- **Tues 3/12 2:00-2:30 PM**
  **Assembly Challenges and Learnings for Large 2.5D TSV Products** by Mike Kelly

- **Tues. 3/12 4:15-4:45 PM**
  **CoC (Chip on Chip) or FtoF (Fact to Face) - POSSUM™ Technology for 3D MEMS and ASIC Eliminating the Need for TSV or Wire Bonding** by Jemmy Sutanto

- **Wed. 3/13 10:00-10:30 AM**
  **Effect of Substrate Layer Variation on Package Warpage** by Brendan Wells, Wei Lin, HyunJin Park

- **Wed. 3/13 11:00-11:30 AM**
  **Adopt Advanced RDL Rule to Apply Flip Chip Packaging for Next Generation Si Technology: Feasibility Study** by Shengmin Wen, KyungRok Park, Patrick Thompson, JeongSeok Lee, HyunJin Park

- **Wed. 3/13 2:30-3:00 PM**
  **A Process Dependent Warpage and Stress Model for 3D Packages Considering Incoming Die / Substrate Warpage and Assembly Process Impacts** by Wei Lin, Ahmer Syed, KiWook Lee, Karthikeyan Dhandapani

- **Wed. 3/13 3:30-4:00 PM**
  **Innovative 3D Structures Utilizing Wafer Level Fan-Out (WLFO) Technology** by Curtis Zwenger
Organized by the International Microelectronics and Packaging Society (IMAPS), the Conference will showcase a vast array of technical information and products from many high-tech companies serving all segments of the industrial, military, aerospace, radar, medical and semiconductor industries. The conference provides a focused technical program with workshop tracks on:

- 2.5D & 3D IC & Packaging
- Flip Chip & Wafer Level Packaging (WLP)
- MEMS & Associated Microsystems
- LED Packaging for Future Solid-State Lighting

Further information can be found at [http://www.imaps.org/devicepackaging](http://www.imaps.org/devicepackaging)